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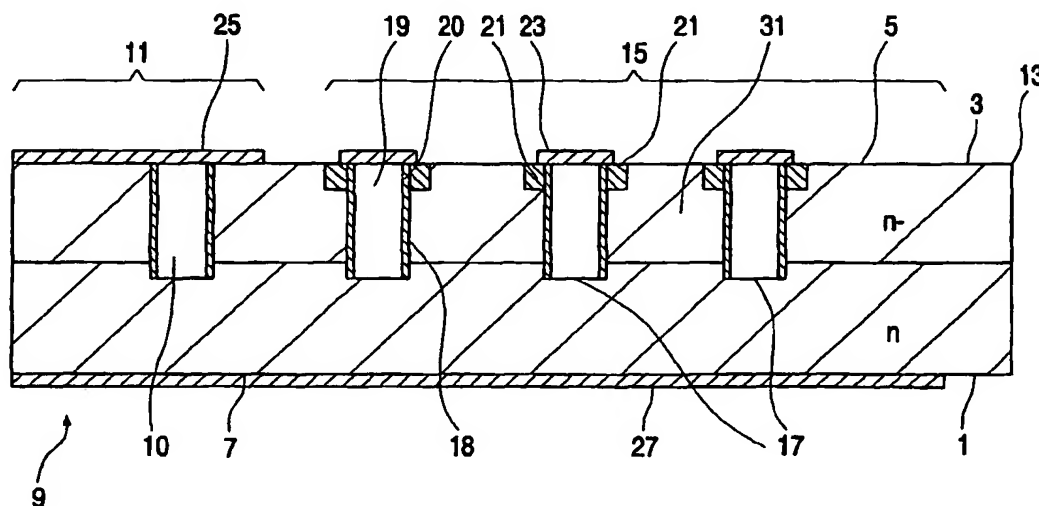
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(54) Title: SEMICONDUCTOR DEVICE WITH EDGE STRUCTURE



(57) Abstract: A semiconductor device has an edge termination region (15) having a plurality of trenches (17). Conductive material (20) and insulating material (19) is formed at the trenches, and surface implants (21) are formed on either side of the trenches. A conductive bridge (23) connects the surface implants (21) to allow equilibrium to be reached in reverse bias.